2025. 2. 7 Date:

Data sheet

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

Style: MLP63C

AEC-Q200 qualified

RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature: +5°C ~ +35°C Relative humidity: 25% ~ 75%

The period of guarantee: Within 2 year from shipmen t by the company.

Solderability shall be satisfied.

- ·Product specification contained in this data sheet are subject to change at any time without notice
- If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

Drawing No: MLP-K-HTS-0004 /1

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1. Scope

1.1 This data sheet covers the detail requirements for metal-plate chip resistor; low ohm, style of MLP63C.

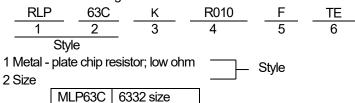
1.2 Applicable documents

JIS C 5201-1: 2011, IEC60115-1: 2008, AEC-Q200 Rev.D

2. Classification

Type designation shall be the following form.

(Example)



3 Temperature coefficient of resistance

| N | ±70×10 ⁻⁶ / °C |
|---|----------------------------|
| K | ±100×10 ⁻⁶ / °C |

4 Rated resistance

| 1L50 | 1.5mΩ |
|------|-------|
| R002 | 2mΩ |

5 Tolerance on rated resistance

| F | ±1% |
|---|-----|
| J | ±5% |

6 Packaging form

| TE | Embossed taping: |
|----|------------------|
| | |

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3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1

| Style | Rated dissipation (W) | Rated current (A) | Temperature resistance | | Rated resistance (mΩ) | Tolerance on rated resistance |
|--------|-----------------------|----------------------|------------------------|-----|-----------------------|-------------------------------|
| | | 54.7 | K | 100 | 1 | |
| | | | N | ±70 | 1 | |
| | | 44.7 | K | 100 | 1.5 | |
| | | 44.7 | N | ±70 | | |
| | | 20.7 | K | 100 | 2 | |
| | | 38.7 | N | ±70 | 2 | |
| | | 34.6 | K | 100 | 2.5 | |
| | | 34.0 | N | ±70 | 2.5 | |
| | | 31.6 | K | 100 | 3 | |
| | 3.0 | 31.0 | N | ±70 | 3 | F(±1%) J(±5%) |
| | | 3.0 | K | 100 | 4 | |
| MLP63C | | | N | ±70 | | |
| | | 24.4 | K | 100 | 5 - 6 | |
| | | | N | ±70 | | |
| | | | K | 100 | | |
| | | 22.0 | N | ±70 | | |
| | | 20.7 | K | 100 | 7 | |
| | | 20.1 | N | ±70 | , | |
| | | 19.3 | K | 100 | 8 | |
| | | 19.5 | N | ±70 | | _ |
| | | 18.2 | K | 100 | 9 | |
| | | | N | ±70 | 9 | |
| | | 17.3 | K | 100 | 10 | |
| | | | 17.5 | N | ±70 | 10 |

| Style | Insulation voltage (V) | Category temperature range (°C) |
|--------|---------------------------|---------------------------------|
| MLP63C | 100 | <i>–</i> 55∼+170 |

3.2 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

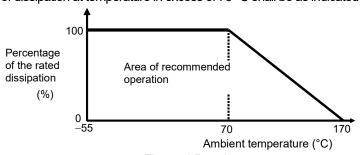


Figure-1 Derating curve

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3.3 Rated voltage

d.c. or a.c. r.m.s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

$$E = \sqrt{P \cdot R}$$

E: Rated voltage (V)

P: Rated dissipation (W)

R: Rated resistance (Ω)

3.4 Rated current

The rated current calculated from the square root of the quotient of the rated resistance and the rated dissipation.

$$I = \sqrt{P/R}$$

I: Rated current (A)

P: Rated dissipation (W)

R: Rated resistance (Ω)

The rated current shall be corresponding to rated voltage.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

| Symbol | Pad | ckaging form | Standard packaging quantity / units |
|--------|-----------------|-------------------------|--|
| TE | Embossed taping | 12mm width, 4mm pitches | 4,000 pcs. |

5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

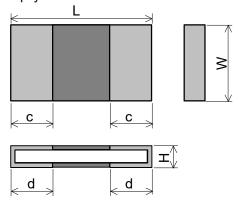


Figure-2

Table-3

Unit: mm

| | Table 6 | | | | | OTTIC: TTIITT |
|--------|--------------------------------|----------|-------------------|-----------|----------|---------------|
| Style | Rated resistance (m Ω) | L | W | Н | С | d |
| | 1 | | 6.3±0.25 3.1±0.25 | 0.38±0.15 | 2.2±0.25 | 2.2±0.25 |
| | 1.5 | | | 0.38±0.15 | 1.5±0.25 | 1.5±0.25 |
| | 2 | | | 0.58±0.15 | 2.2±0.25 | 2.2±0.25 |
| | 2.5 | | | 0.45±0.15 | 2.4±0.25 | 2.4±0.25 |
| | 3 | 6.3±0.25 | | 0.45±0.15 | 2.2±0.25 | 2.2±0.25 |
| MUDGOC | 4 | | | 0.34±0.15 | 2.2±0.25 | 2.2±0.25 |
| MLP63C | 5 | | | 0.51±0.15 | 1.1±0.25 | 1.1±0.25 |
| | 6 | | | 0.5±0.15 | 1.1±0.25 | 1.1±0.25 |
| | 7 | | | 0.5±0.15 | 0.6±0.25 | 0.6±0.25 |
| | 8 | | | 0.35±0.15 | 1.1±0.25 | 1.1±0.25 |
| | 9 | | | 0.35±0.15 | 0.8±0.25 | 0.8±0.25 |
| | 10 | | | 0.35±0.15 | 0.5±0.25 | 0.5±0.25 |



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5.2 Net weight (Reference)

| Style | Rated resistance (mΩ) | Net weight (mg) |
|--------|-----------------------|-----------------|
| | 1 | |
| | 1.5 | |
| | 2 | |
| | 2.5 | |
| | 3 | |
| MLP63C | 4 | 60 |
| | 5 | |
| | 6 | |
| | 7 | |
| | 8 | |
| | 9 | |
| | 10 | |

6. Marking

The rated resistance shall be marked in 4 characters consisting of 3 figures and a letter and marked on over coat side.

(Example) "R010" \rightarrow 0.01 [Ω] \rightarrow 10 [m Ω]

"1L50" \rightarrow 0.0015 [Ω] \rightarrow 1.5 [m Ω]



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7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

| No | Test items | Condition of test | Performance requirements |
|----|---------------------------|--|--------------------------------------|
| | TOCKIONIO | Solidison of too | 1 shermanse requirements |
| 1 | High temperature exposure | MIL-STD-202 Method 108 | Δ R/R: Within ±3% |
| | AEC Q200 - No.3 | Ambient temperature:155±2°C, | No visible damage |
| | | Condition: Without load, | ğ |
| | | Duration: 1,000 +48 h | |
| | | Interval measurements: 250 h and 500 h | |
| 2 | Temperature cycling | JESD22 Method JA-104 | Δ R/R: Within ±3% |
| | AEC Q200 - No.4 | Temperature: -55±3°C / 125±2°C, | No visible damage |
| | | Dwell time: 30min maximum at each temp. | <u> </u> |
| | | Transition time: 1 min. max. | |
| | | Number of cycles: 1,000 cycles. | |
| | | Interval measurements: 250 cy and 500 cy | |
| 3 | Bias humidity | MIL-STD-202 Method 103 | Δ R/R: Within ±3% |
| | AEC Q200 – No.7 | Condition: 85°C & 85% R.H. | No visible damage |
| | | Test power: 10% of rated power shall be applied | |
| | | for continuously. | |
| | | Duration: 1,000 ⁺⁴⁸ ₀ h | |
| | | Interval measurements: 250 h and 500 h | |
| 4 | Operational life | MIL-STD-202 Method 108 | Δ R/R: Within ±3% |
| | AEC Q200 – No.8 | Ambient temperature: 125±2°C | No visible damage |
| | | The applied voltage shall be the voltage to be | |
| | | calculated at 35% of rated dissipation or the | |
| | | limiting element voltage whichever is the smaller. | |
| | | Condition: The voltage shall be applied for | |
| | | continuously. | |
| | | Duration: 1,000 +48 h | |
| | | Interval measurements: 250 h and 500 h | |
| 5 | External Visual | MIL-STD-883 Method 2009 | Inspect device construction, marking |
| | AEC Q200 – No.9 | | and workmanship. |
| | | | |
| 6 | Dimensions | JESD22 Method JB-100 | As in Table–3 |
| | AEC Q200 – No.10 | | |
| 7 | Resistance to Solvents | MIL-STD-202 Method 215 | Δ R/R: Within ±1% |
| | AEC Q200 – No.12 | Solvent: 2-propanol at 25 °C | No visible damage |
| | | Immersion time: 3 min | |
| | | Brush: 10 times brushing | |
| | 100 | Immersion and brush cycle: 3cycle | |
| 8 | Mechanical Shock | MIL-STD-202 Method 213 | ΔR/R: Within ±1% |
| | AEC Q200 – No.13 | Waveform: half sine, | No visible damage |
| | | Peak value100G, | |
| | | Normal duration 6ms | |
| | | Condition: XX'YY'ZZ', 18times total | |

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Table-4(2)

| NIa | Toot itams | Condition of toot | Dorformanaa rasuiramanta |
|-----|------------------------------|--|-------------------------------------|
| No | Test items | Condition of test | Performance requirements |
| 9 | Vibration | MIL-STD-202 Method 204 | Δ R/R: Within ±1% |
| | AEC Q200 – No.14 | Peak acceleration and Sweep time: 5 g's for 20 min , | No visible damage |
| | | Frequency 10Hz to 2000Hz, | |
| 40 | | Condition: 12 cycles each of 3 orientations | |
| 10 | Resistance to soldering heat | MIL-STD-202 Method 210 | Δ R/R: Within ±3% |
| | AEC Q200 - No.15 | Test conditions:K | No visible damage |
| | | Temperature: 250±5 °C | |
| | | Time: 30sec | |
| | | Temperature ramp: 1°C/s-4°C/s | |
| | | immersion and emersion rate : | |
| | | Time above 183°C, 90 s - 120 s | |
| | | The assembly shall be exposed to three heat | |
| 44 | F0D / / | cycles. | |
| 11 | ESD test | AEC-Q200-002 | Δ R/R: Within ±5% |
| | AEC Q200 – No.17 | Human body model, 2 Kohm, 150 pF, | No visible damage |
| | | Test voltage: 12kV | |
| 12 | Solderability | J-STD-002 | The surface of terminal immersed |
| | AEC Q200 - No.18 | B) Bake the sample for 155 °C dwell time 4h / | shall be min. of 95% covered with a |
| | | solder dipping 235°C/5s. | new coating of solder. |
| | | Solder: Sn96.5-Ag3-Cu0.5 | |
| | | B1) Bake the sample for 155 °C dwell time 4h / | |
| | | solder dipping 245°C/5s. | |
| | | Solder: Sn96.5-Ag3-Cu0.5 | |
| 40 | FI 1: 101 1 : 1 | D) Category 3, Solder dipping 260°C/ 30s. | 4 7 |
| 13 | Electrical Characterization | 1. D.C. Resistance | 1. The resistance value shall |
| | AEC Q200 - No.19 | Conform to JIS C 5201-1 4.5 | correspond with the rated |
| | | Mount it on our recommended 4-terminal test | resistance taking into account the |
| | | board and measure the resistance using the | specified tolerance. |
| | | 4-terminal measurement method. | 2. As in Table–1 |
| | | h -x k a | |
| | | Current :Copper dad | |
| | | terminal :Solder resist | |
| | | Voltage terminal | |
| | | Posistones | |
| | | Style Resistance a b c | |
| | | value(m Ω) | |
| | | MLP63C 1,2 to 4 1.8 2.9 3.5 | |
| | | 1.5, 5 to 10 4.0 1.8 5.5 | |
| | | 2. Tamparatura Coofficient of Decistors | |
| | | 2. Temperature Coefficient of Resistance -55 °C / +20°C | |
| | | -55°C/+20°C +20°C/+155°C | |
| 14 | Flammability | UL-94 | V-1 is acceptable |
| 14 | AEC Q200 – No.20 | UL-34 | |
| 15 | Bending strength | AEC-Q200-005 | ΔR/R: Within ±1% |
| 15 | AEC Q200 – No.21 | Bending value2mm | |
| | ALO Q200 — NO.2 I | Holding time: 60sec. | No visible damage |
| 16 | Adhesion | AEC-Q200-006 | ΔR/R: Within ±1% |
| 10 | AEC Q200 – No.22 | Pressurizing force:17.7N | I |
| | | Test time: 60±1s. | No visible damage |
| 1 | | 1001 UH 10. UU 110. | |

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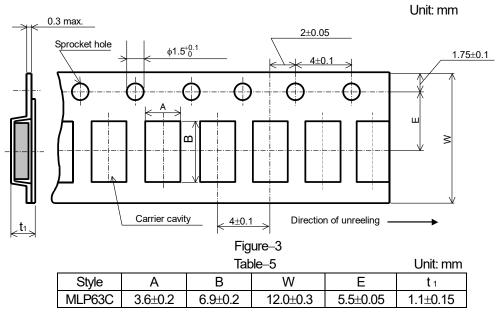
8. Taping

8.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010

8.2 Taping dimensions

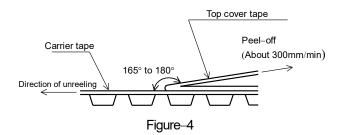
Embossed taping (12mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-3 and Table-5.



- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure-4.
- 6). When the tape is bent with the minimum radius for 30mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

The maximum number of missing components shall be one or 0.1%, whichever is greater.

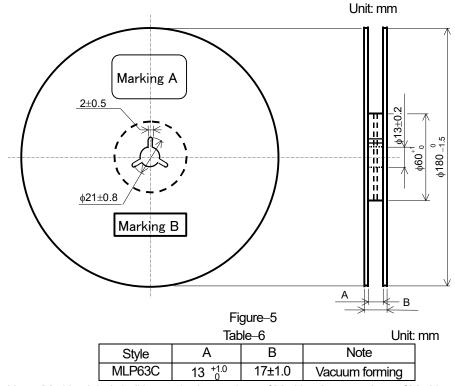


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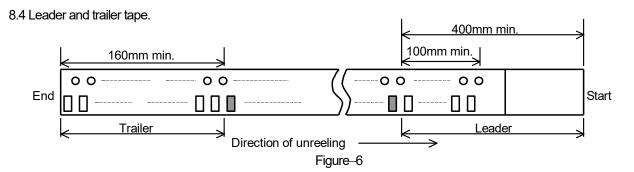
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8.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–5 and Table–6. Plastic reel (Based on EIAJ ET–7200C)



Note: Marking label shall be marked on a place of Marking A or two place of Marking A and B.



9. Marking on package

The label of a minimum package shall be legibly marked with follows.

9.1 Marking A

- (1) Classification
- (Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)
- (2) Lot number (3) Quantity (4) Manufacturer's name or trade mark (5) Others
- 9.2 Marking B (KAMAYA Control label)